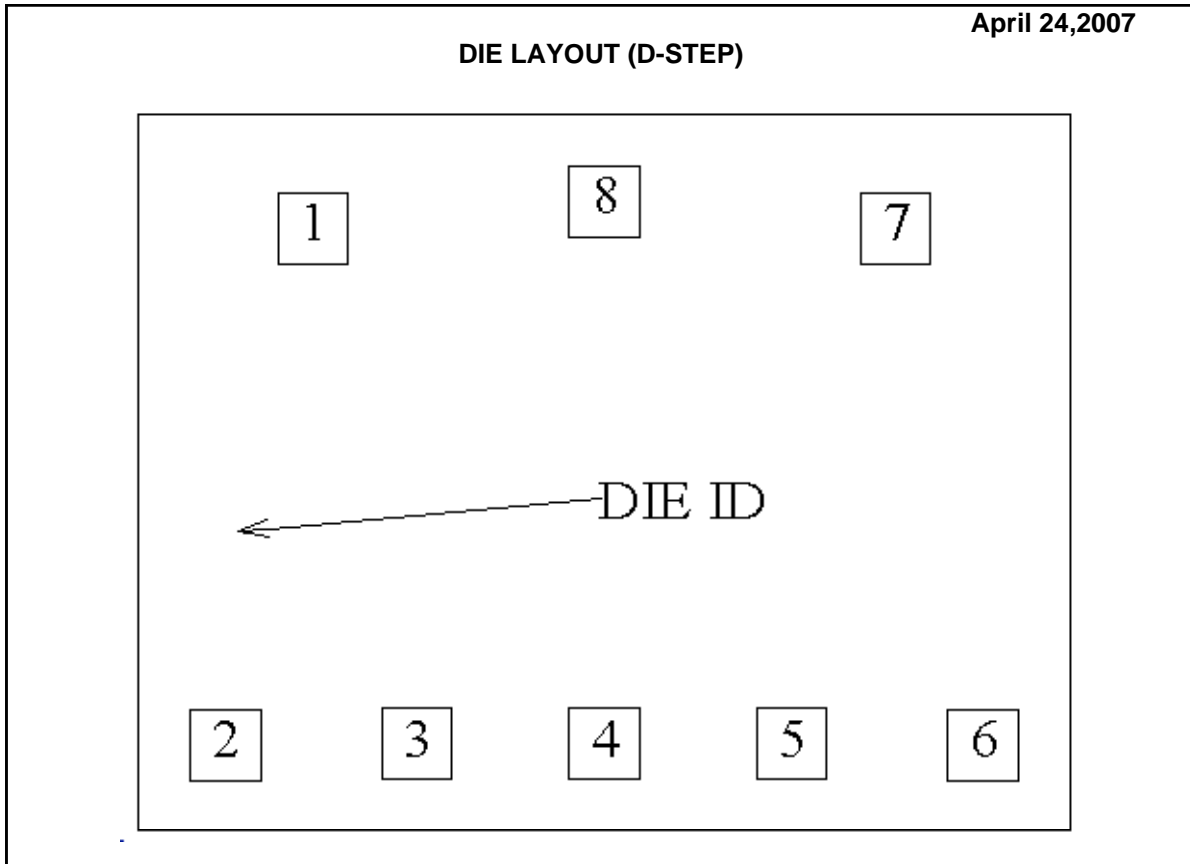


**LM158 MD8 MCD2540A**  
**LOW POWER DUAL OPERATIONAL AMPLIFIER**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LM158	Bond Pad Opening Size (min)	92 $\mu$ m x 92 $\mu$ m
Die Step	D	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1219 $\mu$ m x 940 $\mu$ m 48.0mils x 37.0mils	Back Side Connection	Floating
Thickness	330 $\mu$ m Nominal		
Min Pitch	244 $\mu$ m Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (D-Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
OUTPUT A	1	-381	320	92	x	92
INPUT A -	2	-496	-357	92	x	92
INPUT A +	3	-245	-355	92	x	92
GND	4	0	-355	92	x	92
INPUT B +	5	245	-355	92	x	92
INPUT B -	6	496	-357	92	x	92
OUTPUT B	7	381	320	92	x	92
V+	8	0	355	92	x	92

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